

U.S. UTILITY Patent Application

m. H. OLPE SCANNED <u>1R2</u> <u>AA</u>	PATENT DATE 01/01/01
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APPLICATION NO. 09/687048	CONT/PRIOR F	CLASS 257	SUBCLASS 666T	ART UNIT 25814	EXAMINER D. NGUYEN
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Leadframe and semiconductor package with improved solder joint strength

PTO-2040
12/89[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drawg.	Figs. Drawg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner)		NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____	_____ (Primary Examiner)		ISSUE FEE	
	_____ (Date)		Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Local Instruments Examiner)		ISSUE BATCH NUMBER	

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